



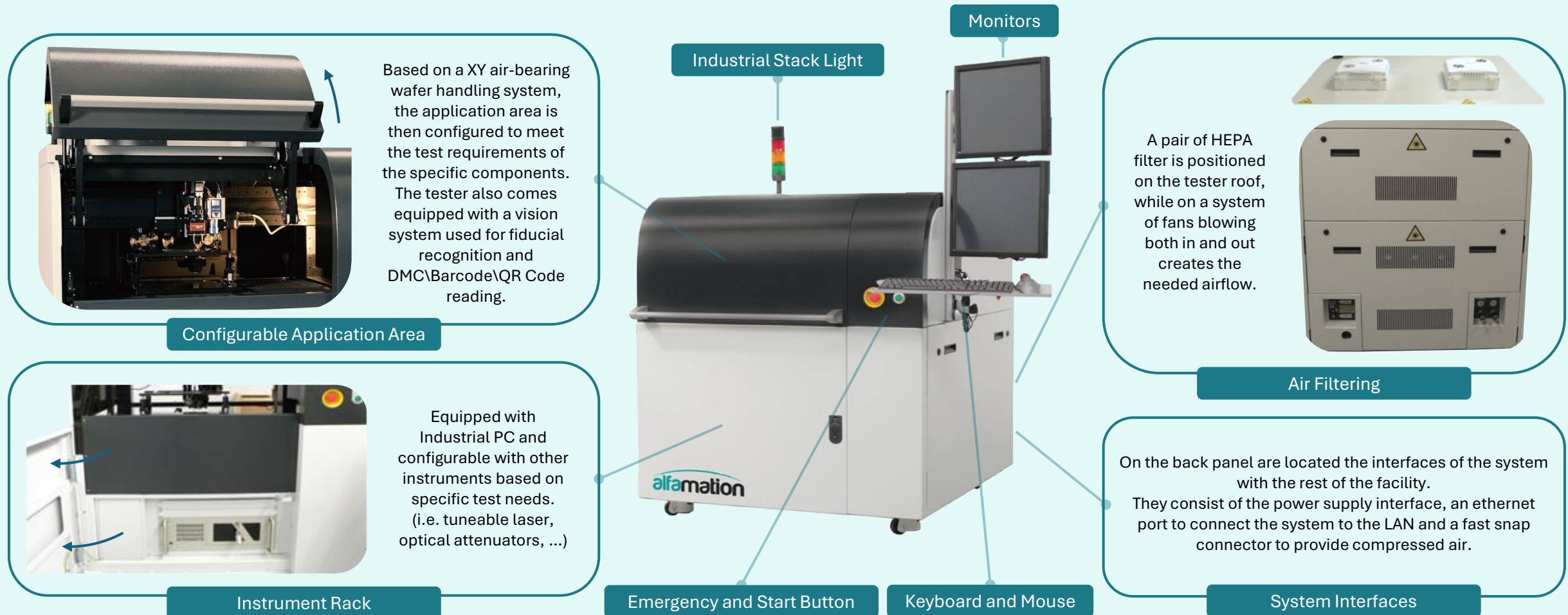
WALOT™

**WAfer Level Optics Tester
Platform Focus**

WALOT™: the fully Automated Wafer-Level Test System

Platform Structure

At Alfamation we offer a **fully automated test system** designed to combine **efficient automation** with the capability of handling a **wide range of functional tests**. The platform is equipped with a high performative and reliable **air-bearing wafer handling system** combined with a **flexible measurement setup architecture** which requires little to no maintenance. The platform is structured as showed below:

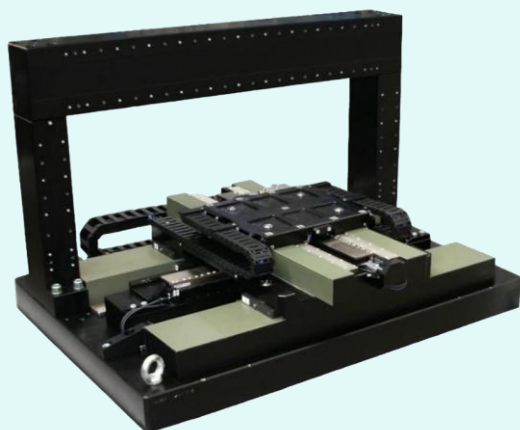


WALOT™ : Platform Structure

Configurable Application Area

The core of the application area is the wafer handling system. This setup is then equipped with a chuck and configured with a set of instruments which depends on the specific elements which needs to be tested.

XY Wafer Handling System

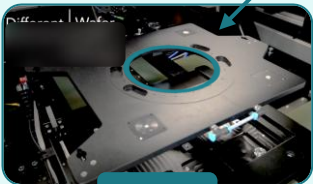
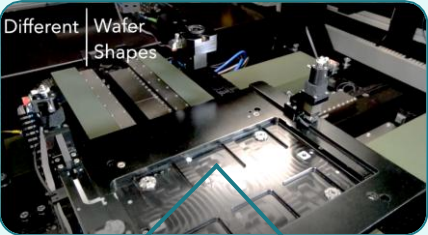


The systems uses aerostatic linear systems with **adjustable flat air bearings** and guideways overlaid by antiseizure material to avoid the risk of blocking the guideways in case of temporary and unexpected overloading. The **portal frame** is used for the application tooling and allows to **preserve the orthogonality of the system**.

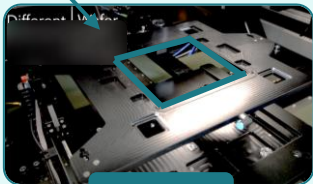
Feature	UM	X axis	Y Axis
Stroke	mm	400	
Maximum Speed	m/s	2	
Maximum Acceleration	m/s ²	1.5	2
Position Repeatability	μm	±0.3	
Position Accuracy	μm/m	±5	
Orthogonality	arcsec	±30	

Chuck

The wafer handling system is than equipped with **pillars** and a **chuck** where the wafer can be loaded either **manually** or with a **wafer handler unit**. **The chuck design** can be **customized** to the specific **wafer layouts** and **test needs**. It is possible to measure wafers with diameters **up to 12"** and with **any shape**. Additional features like **automated wafer rotation**, **automated wafer warpage compensation** or **wafer retention systems** are all realized with the addition of elements **at chuck level**, so the **design of the chuck** really allows for **flexible and diverse implementations**.



Circle

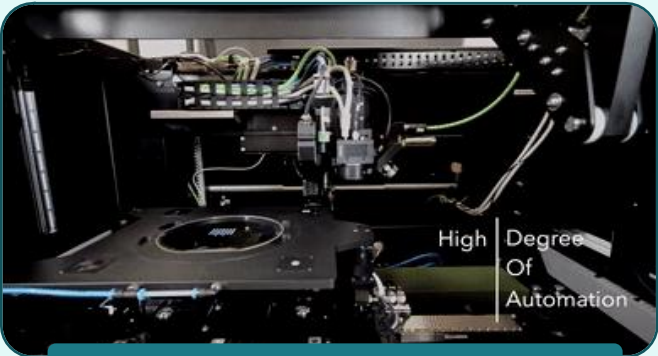


Square

Configurable Application

The portal frame is equipped with the instruments needed to carry out the test tasks. This configuration is dependent on the DUT, but it usually consists of two groups:

1. The **Upper-Group or Analysis Group** where analysis instrument like **industrial cameras**, **distance sensors**, **integrating sphere** or **steering mirrors** are mounted
2. The **Lower Group or Beam Shaper Group**, an **opto-mechanical system** designed to produce on the DUT plane a light signal with specific characteristics (i.e. **Intensity Profile**, **Spatial Correlation**, **Divergence**, **Spot Shape & Dimension**, **Wavelength**, ...).



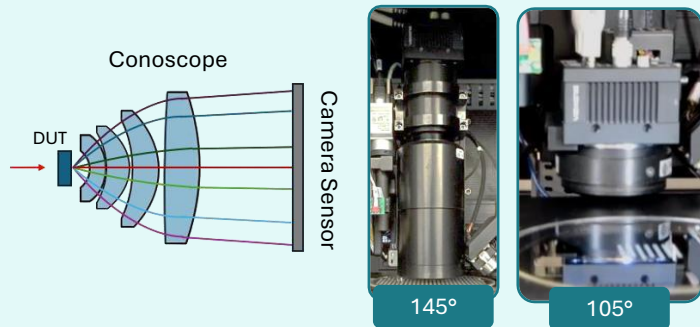
Example - Configured Application Area

WALOT™: Application Area Configurations

Conoscopy Mode

One of the mode the tester can be configured into is the Conoscopy Mode. This setup allows to measure devices such as Diffractive Optical Elements (DOE) and Meta Optical Elements (MOE). These devices have often a large emission angle and thus require specialized optics to be tested.

Upper Group – Analysis Group



The Upper Group or Analysis Group is equipped with a **high-resolution camera** (50 MP) with a **large sensor** (diagonal 35 mm). A specialized optics called **conoscope** is mounted on the camera. This lens system has a **high acceptance angle** and produces an **angular map** of the light emitted by the device on the camera sensor. Alfamation offers **different conoscope designs** with **different fields of view** (from **105° to 145°**) and **different optical resolutions** (down to **0.3°**). The conoscope calibration and characterization is performed directly by Alfamation.

Lower Group – Beam Shaper Group

Alfamation provides different configuration of the Lower Group or Beam Shaper Group depending on the specification of the DUTs.

1. Usually, to test **DOEs**, a single **collimated beam** with a **well-defined spot size and shape** on the DUT plane is sufficient.
2. **MOEs** often combine the diffractive properties of a DOE with collimation, so in this case a **divergent beam** with a **specific numerical aperture** and **additional motorized linear stage to execute a focus scan** procedure are needed.
3. In the **final application**, these devices are usually combined with **VCSEL arrays**, so the beam shaper could be based off these devices too.

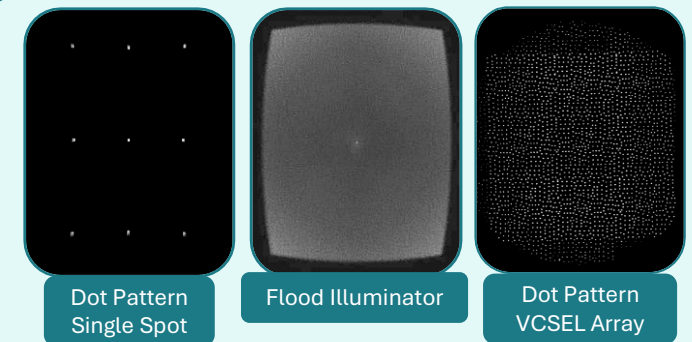
Example - Conoscope Images of different beam shapers



Performance

Test Metrics: Angular Distribution, Transmission Efficiency, Diffraction Efficiency, Uniformity
Speed: Up to **3000 UPH** (Units per hour)
Stability: Gage R&R < 10%

Example – Test Images on Conoscope

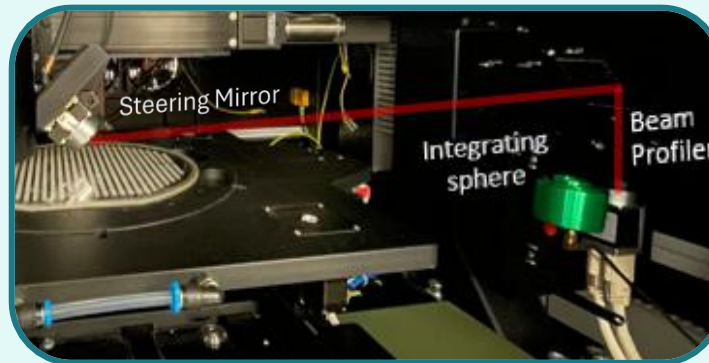
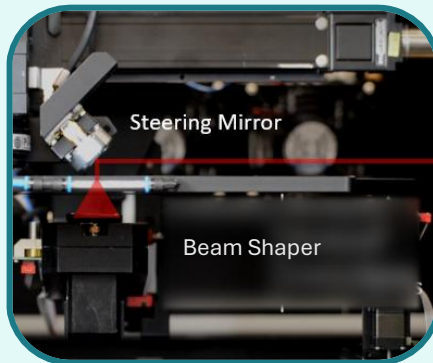


WALOT™ : Application Area Configurations

Collimated Beam Profiling Mode

Another mode the tester can be configured into is the Collimated Beam Profiling Mode. This setup allows to measure collimation lenses such as the ones used combined with Diffractive Optical Elements (DOE). These devices usually require to test the collimation quality far from the DUT.

Upper Group – Analysis Group & Lower Group – Beam Shaper Group



The **Lower Group or Beam Shaper Group** is designed to illuminate the DUTs with a **divergent beam** with **tuneable numerical aperture**. It is completed by a **motorized linear stage** used to move the optical module and allowing to perform a **focus scan** on the devices. The **Upper Group or Analysis Group** is equipped with a **steering mirror**. Its function is to **deflect the beam towards the side instruments**, placed **far from the DUT** itself, at a **configurable distance**. This side instruments usually consist of a **beam profiler** and an **integrating sphere**, which are used to evaluate the collimation quality of the lenses. The steering mirror allows not only to switch the beam destination between the integrating sphere and the beam profiler, but it also allows to perform **off-axis measurements**, by compensating for the output angle of the collimation lenses.

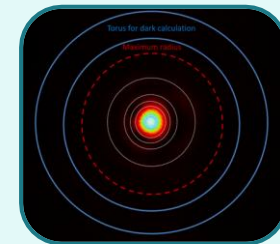


On Axis – Off Axis : Steering

Performance

Test Metrics: Spot Size, Transmitted Power, Flange Focal Length, Effective Focal Length
Speed: Up to 1500 UPH (Units per hour)
Stability: Gage R&R < 10%

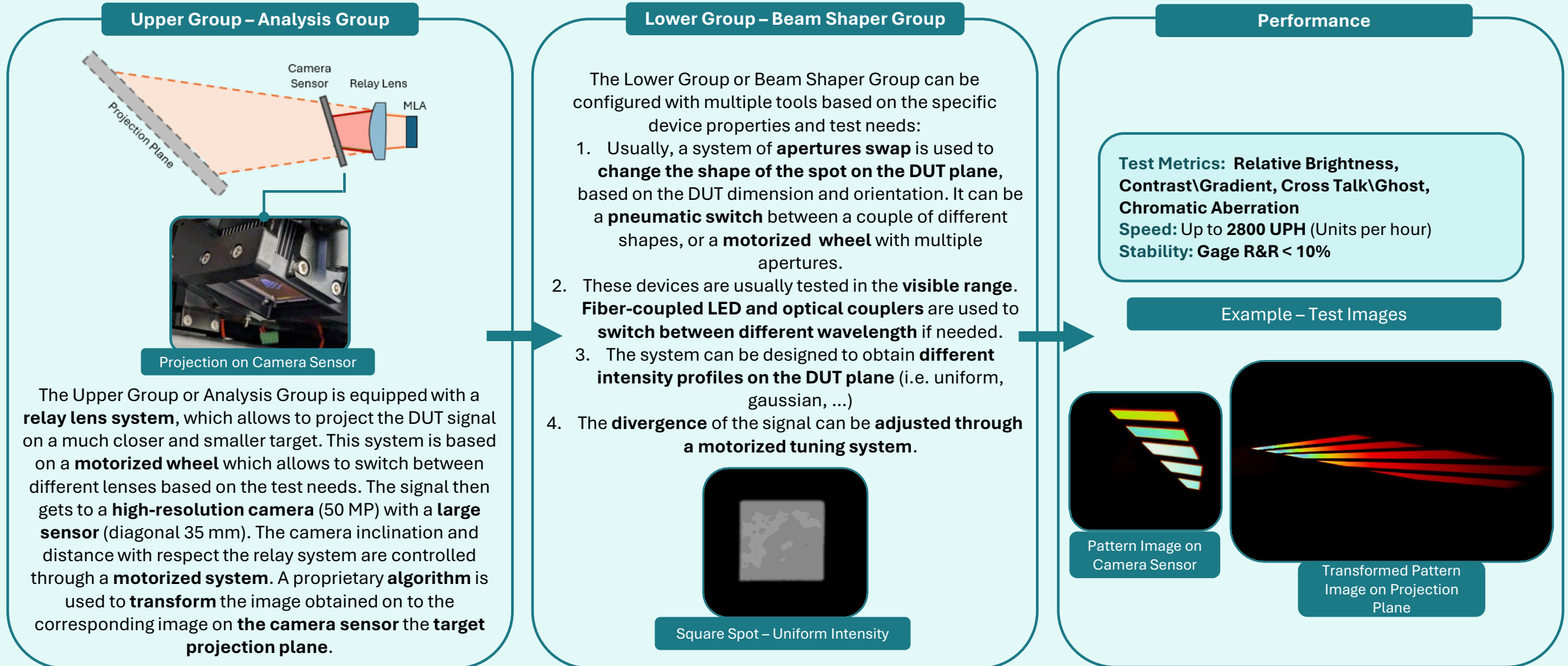
Example – Test Images on Beam Profiler



WALOT™: Application Area Configurations

Light Pattern Projection Mode

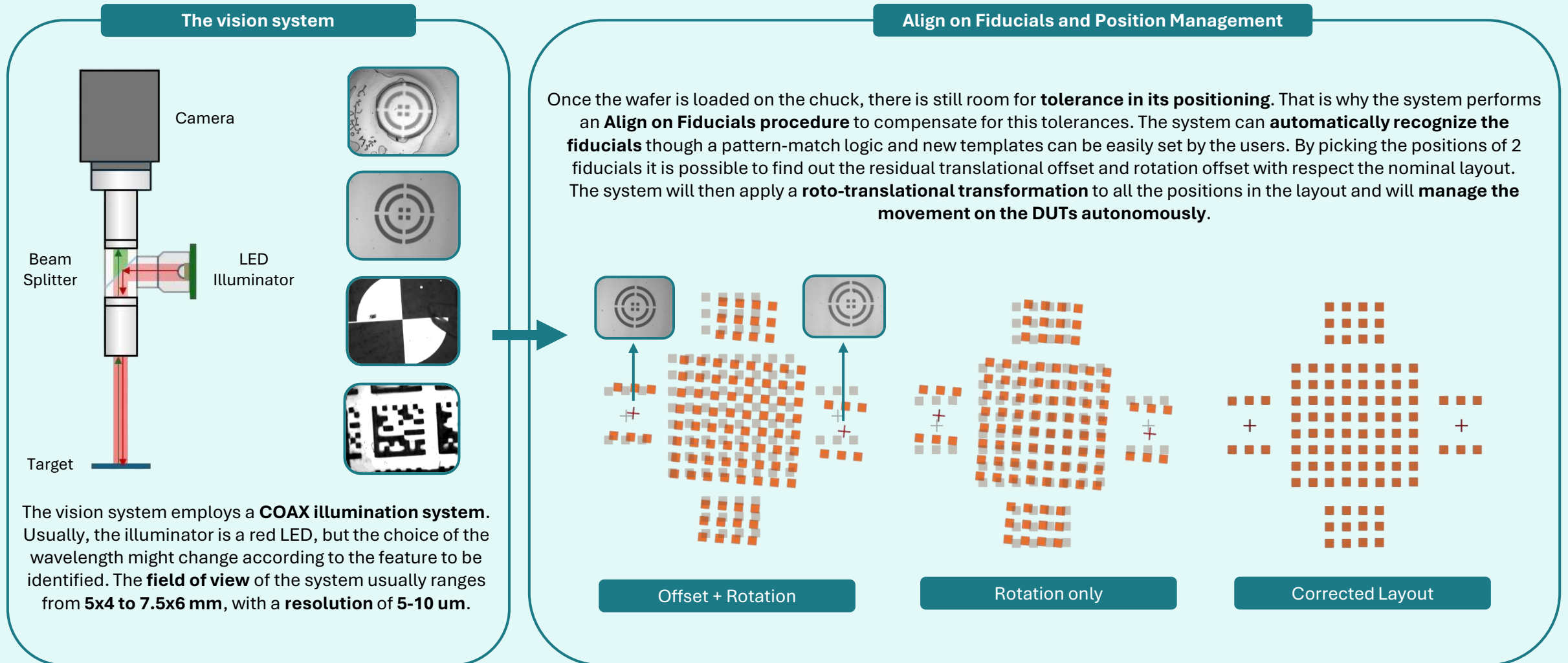
The platform can be configured into the Light Pattern Projection Mode, allowing to test Micro Lens Arrays (MLAs), used for example for vehicle light projection. Due to the working distance and the dimension of the illuminated area of these devices, an optical relay system is used to keep the test environment compact.



WALOT™ : Features

Align on Fiducials and Position Management

The platform is equipped with a vision system which is for alignment purposes and eventually to read Barcodes\QR Codes\DMC and similar.

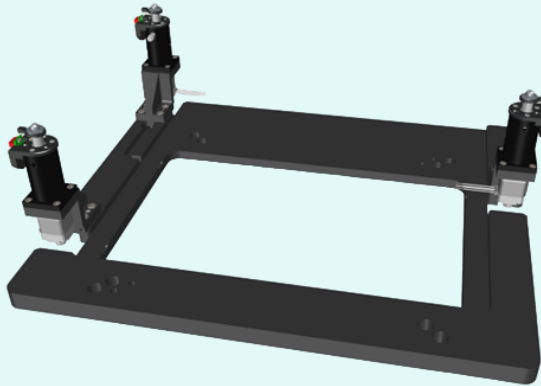


WALOT™: Features

Wafer Warpage Compensation

Once manufactured, wafers usually show a **warpage**, which is **larger the thinnest and wider the wafer** is. The WALOT™ platform can be equipped with a **wafer compensation kit**, which allows to correct locally at each DUT the effect of the residual warpage.

Warpage Compensation Kit



Motorized Chuck Base

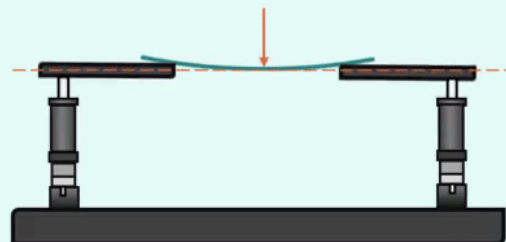
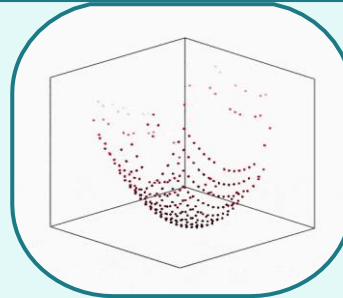
The wafer warpage compensation kit consists of **2 main additions**:

1. **Three linear actuators** replacing the fixed pillars where the chuck is placed. This **motorized chuck base** allows to **fully manipulate the wafer tilt**.
2. A **distance sensor** used to **characterize the wafer warpage**. The choice of the sensor depends on multiple factors ranging from the wafer material and coating to the trade-off of accuracy and costs.

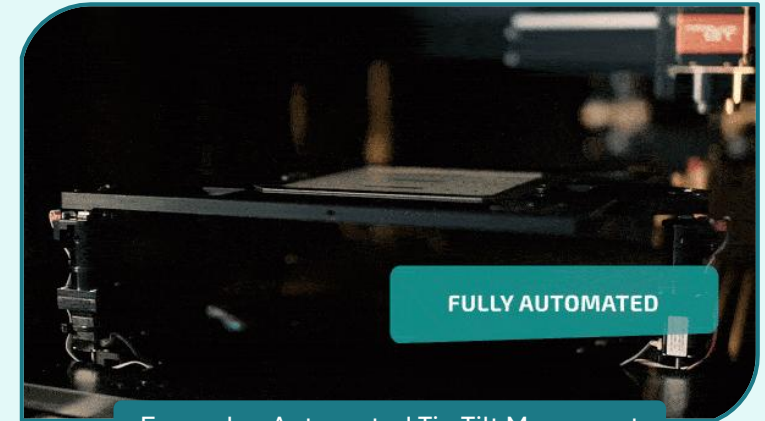
Warpage Compensation Procedure

At the beginning of each run, the system performs a **scan of the wafer to characterize its warpage using a distance sensor**. The result is a layout of the wafer which maps the shape of its surface. Using an algorithm, the position of the three linear actuators of the motorized chuck base can be computed in order to **locally compensate for the wafer warpage at each DUT position**. The compensation is applied in such a way to locally **conserve the overall height of the sample**.

Warpage Characterization



Warpage Compensation – Sample Height Conservation



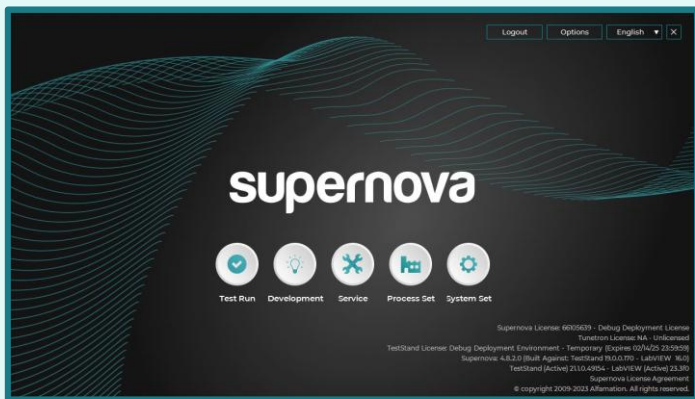
FULLY AUTOMATED

Example - Automated Tip Tilt Movement

WALOT™ : Features

Supernova™ is Alfamation's test sequencer, based on NI TestStand. It provides full control over the test sequence, together with a user-friendly GUI and result management.

Configure the System



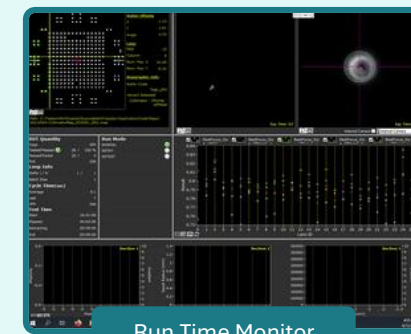
Supernova™ provides multiple tools to fully configure the test environment interface like **Multi-Language** and **Users privileges**. The system is divided in different environments, which allows for an intuitive and modular approach, making it possible to **adjust the test procedure to different kind of devices**. A **Service** environment is present, where debug, **calibration and maintenance** procedures are located. These semi-automatic procedure will **guide the operator step-by-step** with the support of images and examples. The **result management** is entirely integrated in the software, the results are logged on a local SQL database, but it also possible to log on remote location or to interface the system with MES.

Define different Test Variants

Name	Default	SIEMENS36-13225_... SIEMENS36-13225_...
FileGlobals		
TestParameters		
ProductName		SIEMENS36-13225
PathToAlgorithmSettings		C:\TesterInfo\Projects
Pattern	True	True
Ghost	False	True
ChromaticAberration	False	True
Chuck_Rotation	NaN	0
Aperture_Slot	0	6
Aperture_Size	0	9.6
AlignOnDut	False	As Master
DUT_Size		
DUT_SerialNumber_Offset		
Wavelength		
TF_470nm	False	False
TF_554nm	False	False
TF_590nm	False	False
TF_617nm	False	False
TF_660nm	False	False
TF_700nm	False	False
TF_White	True	True
ExposureTime		
Divergence		
Pattern	0	5
Ghost	0	5
ChromaticAberration	0	5
MeasurementsDisplay		

Supernova™ allows to define **different test variants** for different product needs. An intuitive Variants system is in place, allowing to **easily change key test parameters and steps**, giving the user the flexibility to test different devices on the same platform, without major retooling.

Run Tests and Analyse Results



Run Time Monitor



Supernova™ Test Run environment provides an intuitive interface for the user during the test run, showing results, graphs and images live. The results can be then easily analysed thanks to the **Tunetron™** add-on.

Since 2001 DNV ISO 9001 Certified

Since 2003 Certified Registered CSIA Member

Since 2014 Bureau Veritas ISO 9001 (Quality Management) Cert.

Since 2021 Bureau Veritas ISO 45001 (Occupational Health & Safety)

Since 2022 Bureau Veritas ISO 14001 (Environmental Mgmt.)

Since 2023 Bureau Veritas ISO 27001 (Cyber Security)



Install your System Worldwide

Alfamation has been installing test solutions worldwide for more than 30 years.

EMEA: France, Germany, Italy, Portugal, Poland, Czech R., Slovakia, Spain, Belgium, Hungary, Romania, Egypt

Americas: Brazil, Canada, Mexico, USA

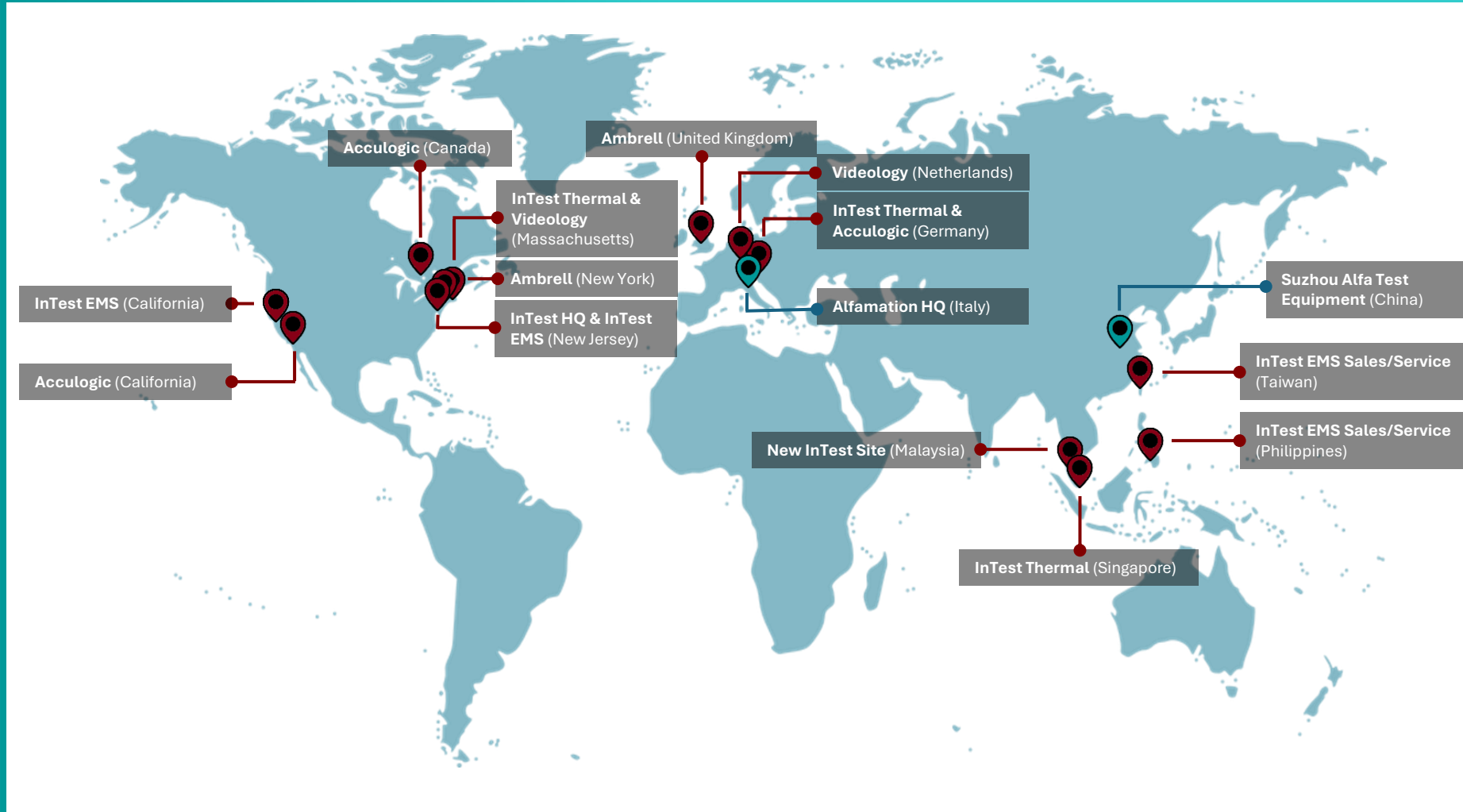
Asia: China, HK, Indonesia, Malaysia, Singapore, Korea, Taiwan, Thailand



Get Support Everywhere

Alfamation has its HQ in Italy and can easily provide support around Europe. An additional office in Suzhou (China) provide service all over Asia.

As a part of InTest Corporation, Alfamation has also access to a network of support which ranges worldwide.



CONTACTS



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